Ceramic Plate Series CP10-127-05-L2-EP-W4.5
MFG Part Number: 58460-503

Ceramic Plate Series Thermoelectric Cooler

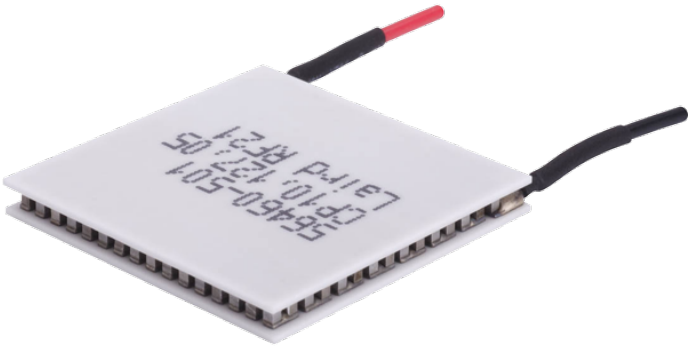
The CP10-127-05-L2-EP-W4.5 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Qc of 33 Watts when ΔT = 0 and a maximum ΔT of 70.5 °C at Qc = 0.

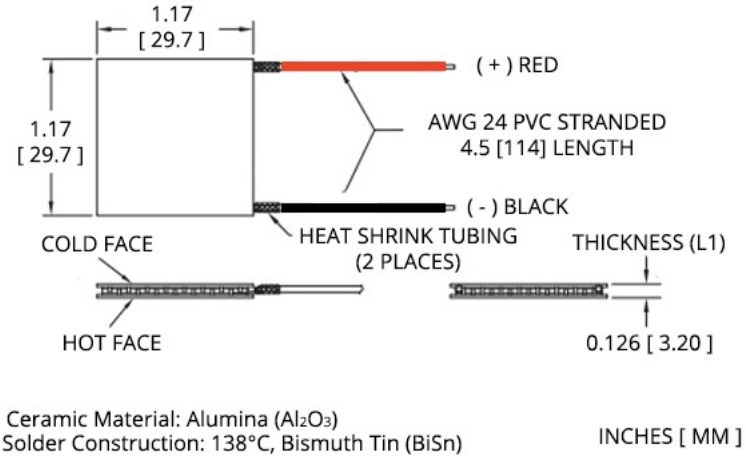
Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant

Applications

- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Heads-Up Displays, Imaging Sensors
- Peltier Cooling for Machine Vision



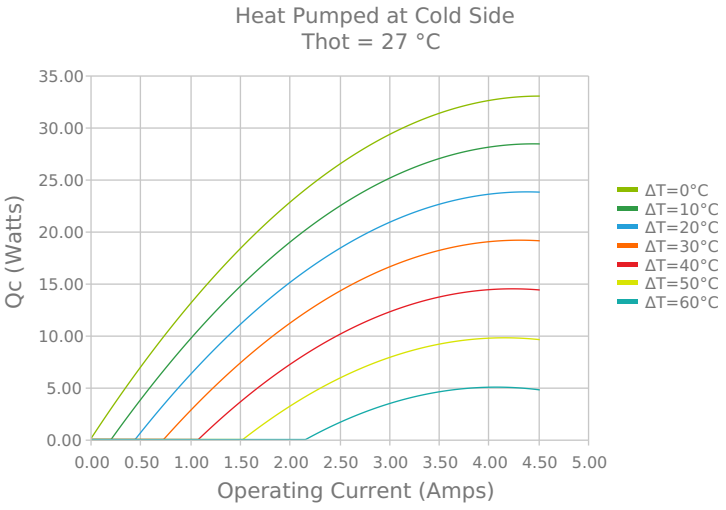


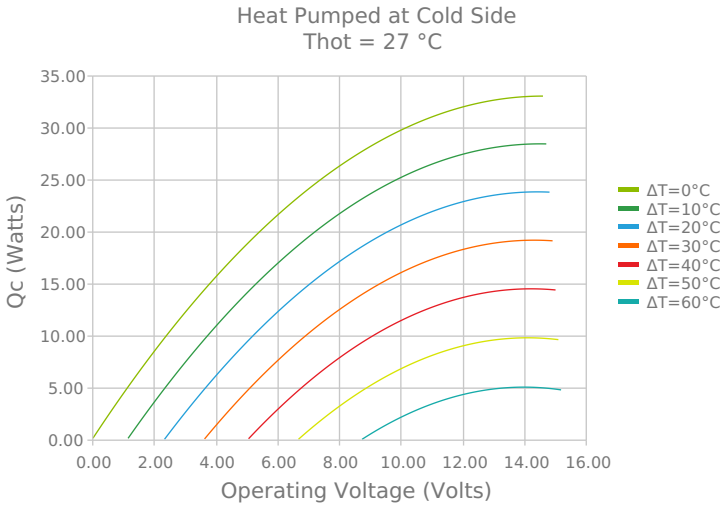
Ceramic Material: Alumina (Al_2O_3)
Solder Construction: 138°C, Bismuth Tin (BiSn)

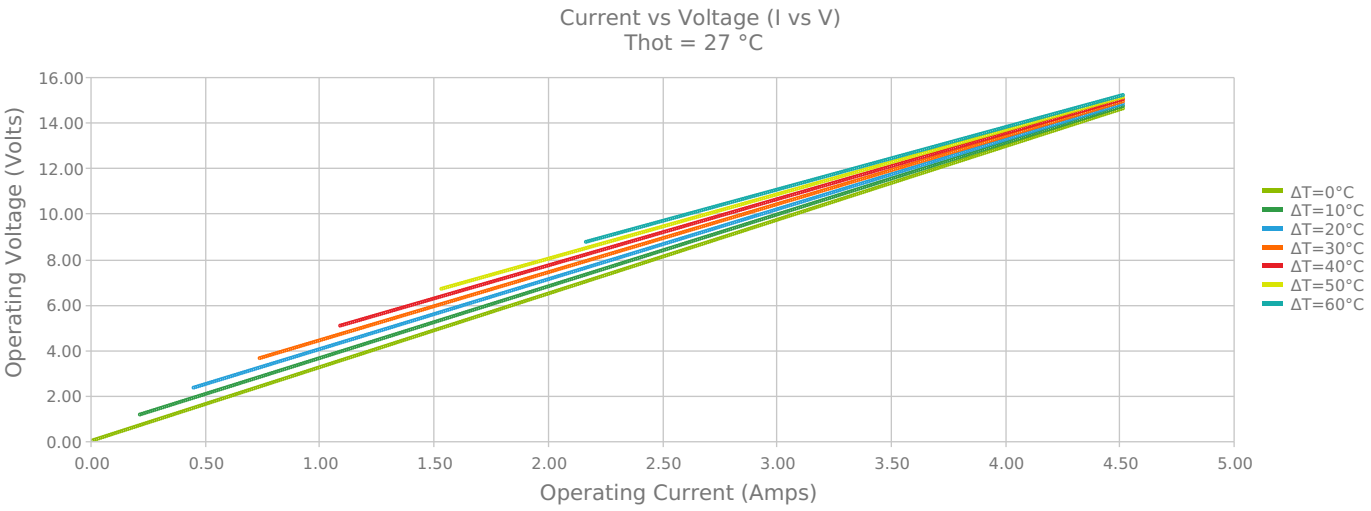
INCHES [MM]

Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

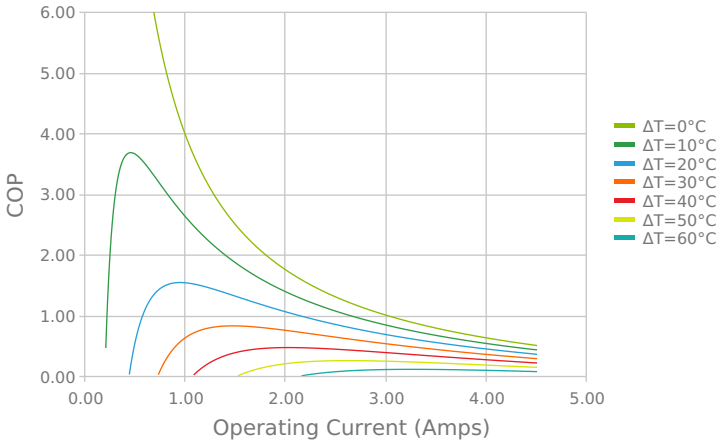
ELECTRICAL AND THERMAL PERFORMANCE







Coefficient of Performance (COP = Qc/Pin)
Thot = 27 °C



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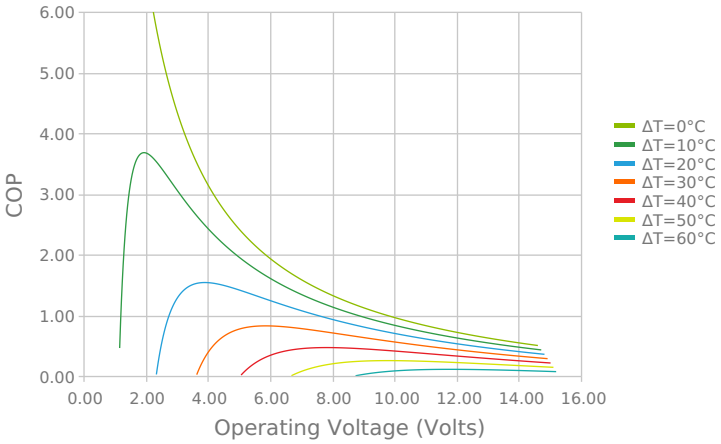
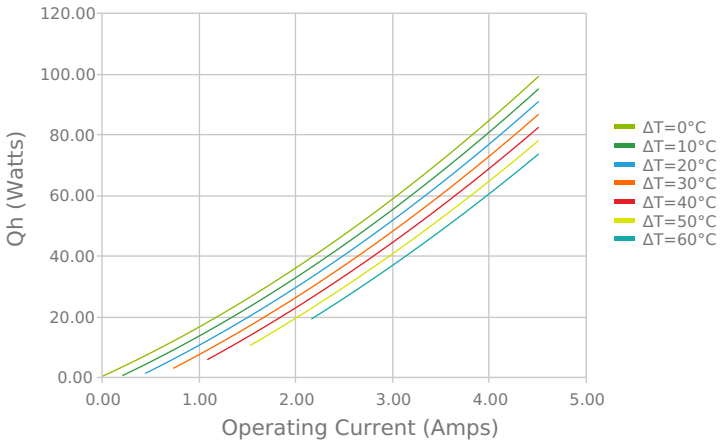


Total Heat Dissipated at Hot Side (Qh=Qc+Pin)
Thot = 27 °C



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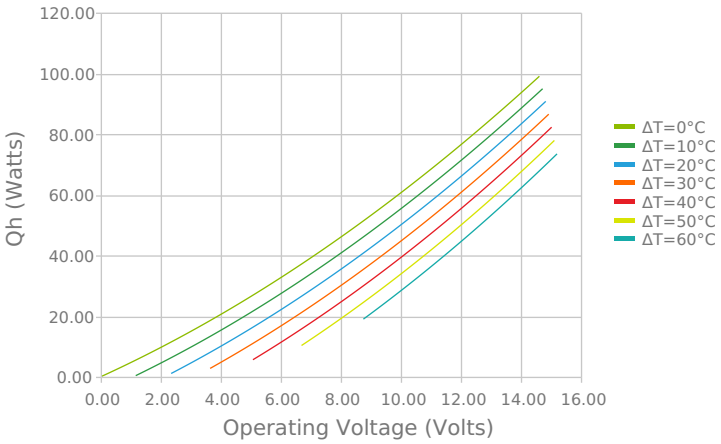
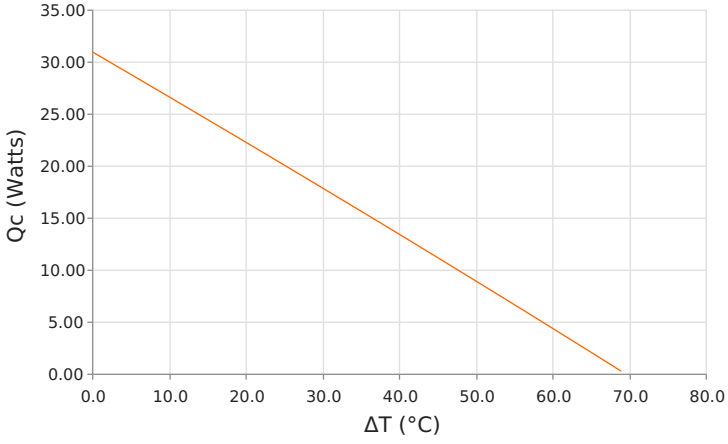
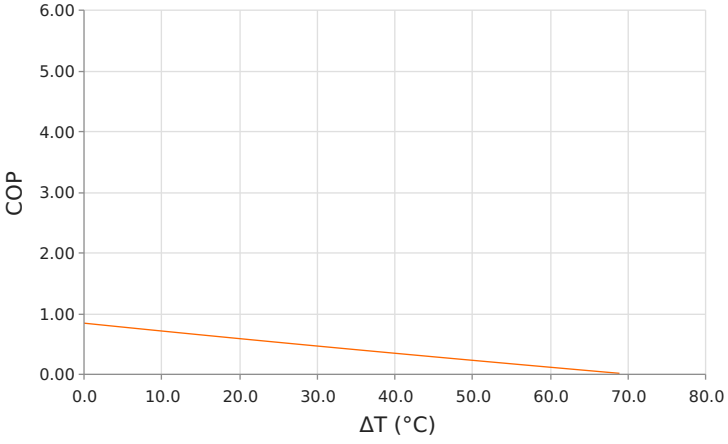


Heat Pumped at Cold Side (Qc)
Thot = 27 °C | Current = 3.4 Amps



Coefficient of Performance (COP = Qc/Pin)
Thot = 27 °C | Current = 3.4 Amps



SPECIFICATIONS*

Hot Side Temperature	27.0 °C	35.0 °C	50.0 °C
Qcmax (ΔT = 0)	33.0 Watts	34.0 Watts	35.8 Watts
ΔTmax (Qc = 0)	70.5°C	73.5°C	78.8°C
Imax (I @ ΔTmax)	4.0 Amps	4.0 Amps	3.9 Amps
Vmax (V @ ΔTmax)	13.9 Volts	14.4 Volts	15.4 Volts
Module Resistance	3.24 Ohms	3.37 Ohms	3.62 Ohms
Max Operating Temperature	80 °C		
Weight	9.0 gram(s)		

* Specifications reflect thermoelectric coefficients updated March 2020

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
L2	3.200 ±0.013 mm 0.126 ± 0.001 in	0.013 mm / 0.013 mm 0.0005 in / 0.0005 in	Lapped	Lapped	114.3 mm 4.50 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
EP	Epoxy	Black	-55 to 150°C	Low density syntactic foam epoxy encapsulant

NOTES

1. Max operating temperature: 80°C
2. Do not exceed Imax or Vmax when operating module
3. Reference assembly guidelines for recommended installation
4. Solder tinning also available on metallized ceramics

Date: 04/24/2020